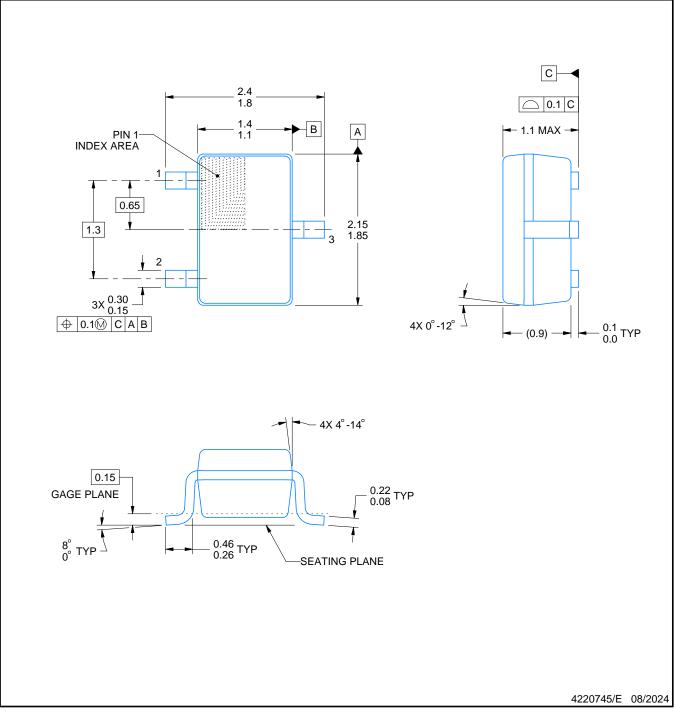
DCK0003A



PACKAGE OUTLINE

SOT-SC70 - 1.1 max height

SMALL OUTLINE TRANSISTOR SC70



NOTES:

- 1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M. 2. This drawing is subject to change without notice. 3. Body dimensions do not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed
- 0.25mm per side

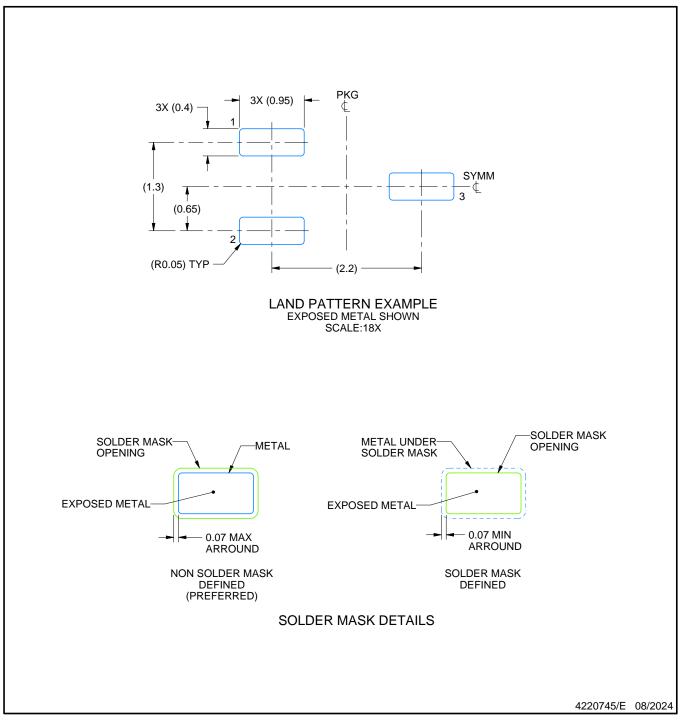


DCK0003A

EXAMPLE BOARD LAYOUT

SOT-SC70 - 1.1 max height

SMALL OUTLINE TRANSISTOR SC70



NOTES: (continued)

4. Publication IPC-7351 may have alternate designs.5. Solder mask tolerances between and around signal pads can vary based on board fabrication site.

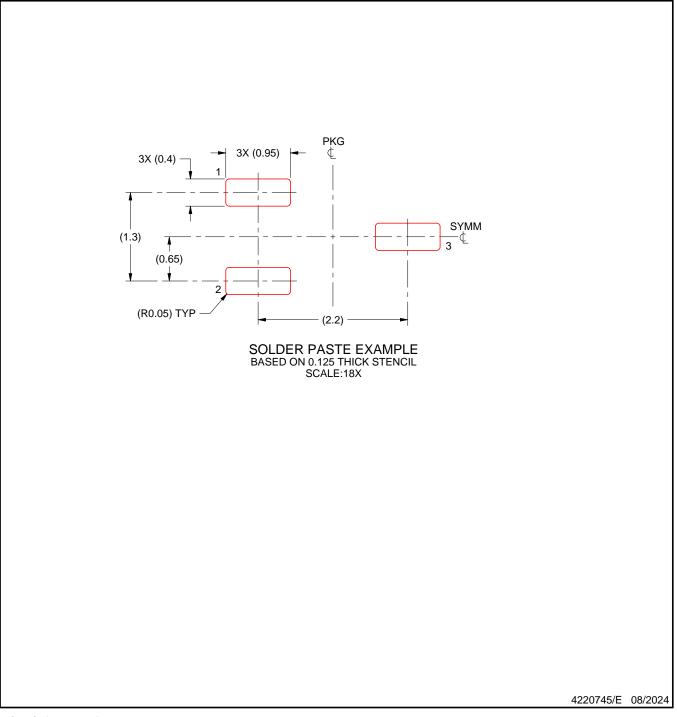


DCK0003A

EXAMPLE STENCIL DESIGN

SOT-SC70 - 1.1 max height

SMALL OUTLINE TRANSISTOR SC70



NOTES: (continued)

7. Board assembly site may have different recommendations for stencil design.



^{6.} Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.

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